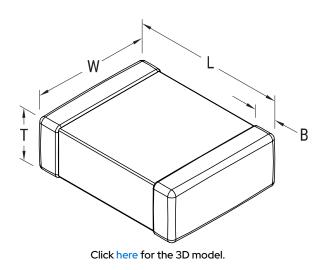




CBR-SMD RF COG, Ceramic, 6 pF, +/-0.5 pF, 250 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0603



General Information		
Series	CBR-SMD RF COG	
Style	SMD Chip	
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I	
Features	Ultra High Q, Low ESR, Class I	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	5.29 mg	
Notes	Solder Wave or Solder Reflow.	
Shelf Life	78 Weeks	
MSL	1	

6 pF

Dimensions	
Chip Size	0603
L	1.6mm +/-0.1mm
W	0.8mm +/-0.1mm
Т	0.8mm +/-0.07mm
В	0.4mm +/-0.15mm

W	0.8mm +/-0.1mm	Voltage DC	250 VDC
Т	0.8mm +/-0.07mm	Dielectric Withstanding Voltage	500 VDC
В	0.4mm +/-0.15mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.192%
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Hour
Packaging Quantity	4000	Insulation Resistance	10 GOhms

L	1.6mm +/-0.1mm	Tolerance	+/-0.5 pF
W	0.8mm +/-0.1mm	Voltage DC	250 VDC
Т	0.8mm +/-0.07mm	Dielectric Withstanding Voltage	500 VDC
В	0.4mm +/-0.15mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.192%
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Hour
Packaging Quantity	4000	Insulation Resistance	10 GOhms
		Quality Factor	520

**Specifications** Capacitance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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